

LNPTM THERMOCOMPTM COMPOUND UFOOASW

UF-100-10 A HS HW

DESCRIPTION

LNP THERMOCOMP UF00ASW compound is based on Polyphthalamide (PPA) resin containing 50% glass fiber. Added features of this grade include: Heat Stabilized, Hot Water Moldable.

GENERAL INFORMATION	
Features	Heat Stabilized, High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polyphthalamide (PPA)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Automotive	Automotive Under the Hood
Consumer	Commercial Appliance
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

PROPERTIES TYPICAL VALUES UNITS **TEST METHODS** MECHANICAL⁽¹⁾ Flexural Stress, yld, 1.3 mm/min, 50 mm span 335 ASTM D790 MPa Flexural Stress, brk, 1.3 mm/min, 50 mm span 337 MPa ASTM D790 ASTM D790 17500 Flexural Modulus, 1.3 mm/min, 50 mm span MPa ISO 527 Tensile Stress, yield, 5 mm/min 214 MPa Tensile Stress, break, 5 mm/min 214 MPa ISO 527 ISO 527 Tensile Strain, yield, 5 mm/min 1.4 % 1.4 % ISO 527 Tensile Strain, break, 5 mm/min Tensile Modulus, 1 mm/min 19060 MPa ISO 527 MPa Flexural Stress 324 ISO 178 Flexural Modulus, 2 mm/min 17240 MPa ISO 178 IMPACT (1) Izod Impact, unnotched, 23°C 788 J/m ASTM D4812 91 Izod Impact, notched, 23°C J/m ASTM D256 Multiaxial Impact 3 ISO 6603 Instrumented Dart Impact Total Energy, 23°C 6 T. ASTM D3763 45 Izod Impact, unnotched 80*10*4 +23°C ISO 180/1U kJ/m² Izod Impact, notched 80*10*4 +23°C 9 ISO 180/1A kJ/m² THERMAL (1) HDT, 0.45 MPa, 3.2 mm, unannealed 297 °C ASTM D648 °C ASTM D648 HDT, 1.82 MPa, 3.2mm, unannealed 285

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CHEMISTRY THAT MATTERS

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PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
CTE, -40°C to 40°C, flow	2.4E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	4.3E-05	1/°C	ASTM E831
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	296	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	281	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Specific Gravity	1.65	-	ASTM D792
Density	1.65	g/cm³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.27	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.2 – 0.5	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.6 - 0.9	%	ASTM D955
Moisture Absorption (23°C / 50% RH)	0.33	%	ISO 62
INJECTION MOLDING (3)			
Drying Temperature	120	°C	
Drying Time	4	Hrs	
Melt Temperature	320 – 350	°C	
Front - Zone 3 Temperature	325 – 330	°C	
Rear - Zone 1 Temperature	315 – 320	°C	
Mold Temperature	50 – 105	°C	
Back Pressure	0.2 – 0.5	MPa	
Screw Speed	30 - 60	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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